



Selected Papers from the 2017 International Conference on Inventions

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Deadline for manuscript submissions:

closed (30 June 2018)

Message from the Guest Editors

Dear Colleagues,

The 2017 International Conference on Inventions (ICI conference) aims to make researchers focus on patent-based research. The invention process is a process within an overall engineering and product-development process. It may be an improvement on a machine or product, or a new process for creating an object or a result. Such works are novel and not obvious to others skilled in the same field. ICI conference aims to gather and show high-quality papers concerning the discovery of completely unique functions or results, and going further to advance the frontiers of science and extend the standards of excellence established by inventions to readers. High quality paper will be recommended to the Special Issue "Selected Papers from the 2017 International Conference on Inventions" in Applied Sciences.

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Guest Editors





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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